APPLICABLE STANDARD					
RATING	OPERATING TEMPERATURE RANGE	-35 ℃ TO +85 ℃(NOTE1)	STORAGE TEMPERATURE RANGE		-10 ℃ TO +60 ℃(NOTE3)
	OPERATING HUMIDITY RANGE	40% TO 80% (NOTE2)	STORAGE HUMIDITY RANGE		40% TO 70% (NOTE3)
	VOLTAGE	250 V AC	APPLICABLE CONNECTOR		DF1E-*S-2.5C
	CURRENT	AWG20 TO 24: 3A AWG26: 2A AWG28: 1A AWG30: 0.5A	UL, CSA	VOLTAGE	AC 30V
				CURRENT	AWG20 TO 22: 3A AWG24 TO 28: 1A AWG30: 0.5A

SPECIFICATIONS

ITEM	TEST METHOD	REQUIREMENTS	QT	AT
CONSTRUCTION				
GENERAL EXAMINATION	VISUALLY AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWING.	X	X
MARKING	CONFIRMED VISUALLY.		X	X
ELECTRIC CHARACTERISTICS				
CONTACT RESISTANCE MILLIVOLT LEVEL METHOD.	20 mV MAX, 1 mA(DC OR 1000 Hz).	30 mΩ MAX.	X	—
INSULATION RESISTANCE	500 V DC.	1000 MΩ MIN.	X	—
VOLTAGE PROOF	650 V AC FOR 1 min.	NO FLASHOVER OR BREAKDOWN.	X	—
MECHANICAL CHARACTERISTICS				
MECHANICAL OPERATION	30TIMES INSERTIONS AND EXTRACTIONS.	① CONTACT RESISTANCE: 30 mΩ MAX. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	–
VIBRATION	FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2 h, FOR 3 DIRECTIONS.	① NO ELECTRICAL DISCONTINUITY OF 1 μs. ② NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	–
SHOCK	490 m/s^2 DURATION OF PULSE 11 ms AT 3 TIMES FOR 3 DIRECTIONS.		X	–
ENVIRONMENTAL CHARACTERISTICS				
RAPID CHANGE OF TEMPERATURE	TEMPERATURE -55→ 5 TO 35→+85→ 5 TO 35 ℃ TIME 30→ 5 MAX→ 30→ 5 MAX min UNDER 5 CYCLES.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 1000 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	–
DAMP HEAT (STEADY STATE)	EXPOSED AT 40 ± 2 ℃, 90 TO 95 %, 96 h.	① CONTACT RESISTANCE: 30 mΩ MAX. ② INSULATION RESISTANCE: 500 MΩ MIN. ③ NO DAMAGE, CRACK OR LOOSENESS OF PARTS.	X	–
RESISTANCE TO SOLDERING HEAT	1) AUTOMATIC SOLDERING (FLOW) SOLDER TEMPERATURE, 260 ℃ FOR IMMERSION,DURATION, 10 sec. 2) MANUAL SOLDERING SOLDERING IRON TEMPERATURE : 300 ℃, SOLDERING TIME : 3 sec. NO STRENGTH ON CONTACT.	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.	X	–
SOLDERABILITY	SOLDERED AT SOLDER TEMPERATURE, 235 ℃ FOR INSERTION DURATION, 5 s.	SOLDER SHALL COVER A MINIMUM OF 95 % OF THE SURFACE BEING IMMERSED	X	–

REMARKS

NOTE1: INCLUDE THE TEMPERATURE RISING BY CURRENT.

NOTE2:NO CONDENSING.

NOTE3:APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE PCB ON BOARD. AFTER PCB BOARD,OPERATING TEMPERATURE AND HUMIDITY RANGE IS APPLIED FOR INTERIM STORAGE DURING TRANSPORTATION.

	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
△0					

Unless otherwise specified, refer to IEC 60512.

APPROVED	KI.AKIYAMA	15.05.29
CHECKED	TS.FUKUSHIMA	15.05.29
DESIGNED	TS.KUMAZAWA	15.05.29
DRAWN	MI.SAKIMURA	15.05.28

TO

Note QT:Qualification Test AT:Assurance Test X:Applicable Test		DRAWING NO.	ELC-161951-35-00		
HRS	SPECIFICATION SHEET	PART NO.	DF1E-*P-2.5DS(35)		
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL541	△0	1/1

FORM HD0011-2-1